

Date: 2005.06.07.

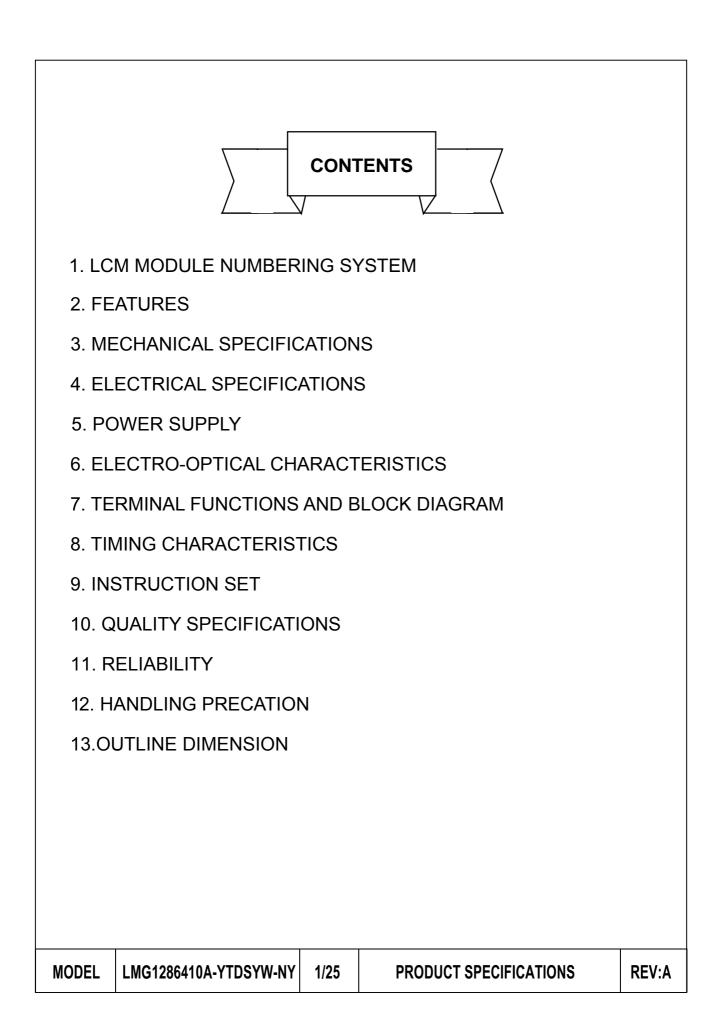
Specifications for Approval

Customer

Model name : LMG1286410A-YTDSYW-NY REV: A

Description : LIQUID CRYSRAL DISPLAY MODULE

DESIGN	CHECK	APPROVED



1. LCM	MODULE NUMBER	RING SY	STEM	
PAR	T NUMBER: LMAx.	yB-CI	DEFGHI-JK	
L: M:	MODULE		CHARACTER TYPE	
A.	DISILAT CONTENTS	G	GRAPHIC TYPE SEGMENT TYPE	
x y:	COLUMNS SERIALS N DISTRIBUTE	Vs. ROW NUMBER ACCORD	'S FOR GM FOR SM	
	VERSION OF D D TYPE:			
	FFSTN		GGRAY STN BBLUE STN TTN	
	M TRANSMI	SSIVE	TRANSFLECTIVE	
	EWING TEMPRETURE U 12:00 I CKLIGHT TYPE:		L 9:00 R 3:00	
Г: DA			SIDE LED E EL C CCF	L
	DLOR OF BACKLIGHT YYELLOW W WHITE ERATING TEMPRETU	/GREEN (G GREEN B BLUE D ORANGE A AMBER	
	N NORMAI NOTE DIFFERENT CHA	., W H ARACTER	EXTENDED , X:ESPECIALLY EXT A TABLE: G TAB , G COG	ENDED
–JK:	K: CHARACT		066U B SPLC780 EROOM SEQUENCE NUMBER	
	FOR GM: J: BACKLIGH Y	IT DRIVE WITH	R N WITHOUT	
	K: DC-DC CO		R N WITHOUT	
MODEL	LMG1286410A-YTDSYW-N	Y 2/25	PRODUCT SPECIFICATIONS	REV:A

2. FEATURES

The features of LCD are as follows

* Display mode	: STN, Positive. Tra	ansflective
----------------	----------------------	-------------

* Color : Display dot : Dark Blue

Background: Yellow / Green

- * Display format : 128 Dots X 64 Dots
- * Interface Input Data : 8-Bit
- * Driving Method : 1/64 Duty, 1/9 Bias
- * Viewing Direction : 6 O'clock
- * Backlight : LED Unit (Yellow-Green)
- * Drive IC : Samsung KS0107/KS0108

3. MECHANICAL SPECIFICATIONS

Item	Specification	Unit
Module Size	75.00(W) x 55.0(H) x 9.00(T)	mm
Number of Dots	128(W) x 64(H) Dots	mm
Viewing Area	60.00(W) x 32.00(H)	mm
Effective display area	55.01(W) x 27.49(H)	mm
Dot Size	0.40(W) x 0.40(H)	mm
Dot Pitch	0.43(W) x 0.43(H)	mm

4. ELECTRICAL SPECIFICATIONS

4-1 ABSOLUTR MAZIMUM RATINGS (Ta = 25 °C)

Item Symbol Supply Voltage For Logic VDD – Vss 0 Supply Voltage For LCD Drive V _{OP} = VDD – V0 0 Input Voltage V1 Vs	Sta	Standard Value			
nem	Symbol	Min.	Тур.	Max.	Unit
Supply Voltage For Logic	Vdd – Vss	0	_	5	V
Supply Voltage For LCD Drive	V _{OP} = VDD – V0	0	-	9	V
Input Voltage	V1	Vss	-	Vdd	V
Operating Temp.	Тор	-20	-	+70	°C *
Storage Temp.	Tst	-30	-	+80	°C

*. NOTE: The response time will be extremely slow when the operating temperature is around -20° C, and the back ground will become darker at high temperature operating.

DEL LMG1286410A-YTDSYW-N

4-2 ELECTICAL CHARACTERISTICS

ltem		Symbol	Test Condition	Min.	Тур.	Max.	Unit
Logic supply	Voltage	Vdd - Vss		4.5	5.0	5.5	V
LCD Drive		V _{OP} =V _{DD} - V ₀	-	-	9.0	-	V
	"H" Level	V IH	VDD=5.0V±5%	0.8 Vdd		Vdd	V
Input Voltage	"L" Level	V IL		0		0.2Vdd	V
Frame Frec	luency	fFLM	VDD =5.0V	65	78	85	Hz
Current Consumption		IDD	V _{DD} = 5.0V V _{DD} -V ₀ =9.0V V/R=160Kohm		1.60	3.0	mA

4-3. BACKLIGHT

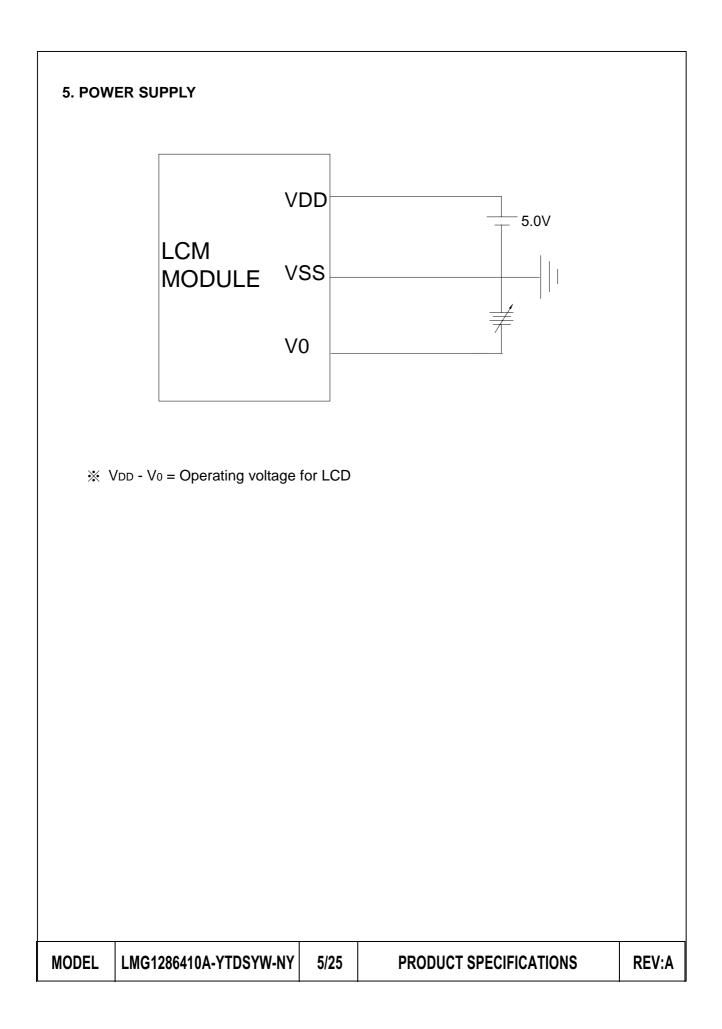
4-3-1. Absolute Maximum Ratings

ltem	Symbol	Condition	Min.	Тур.	Max	Unit
Forward Current	IF	Ta= 25 ℃	-	40	80	mA
Reverse Voltage	VR	1 a- 25 C	-	-	4.2	V
Power Dissipation	PD	Ta= 25 ℃	-	-	80	mW

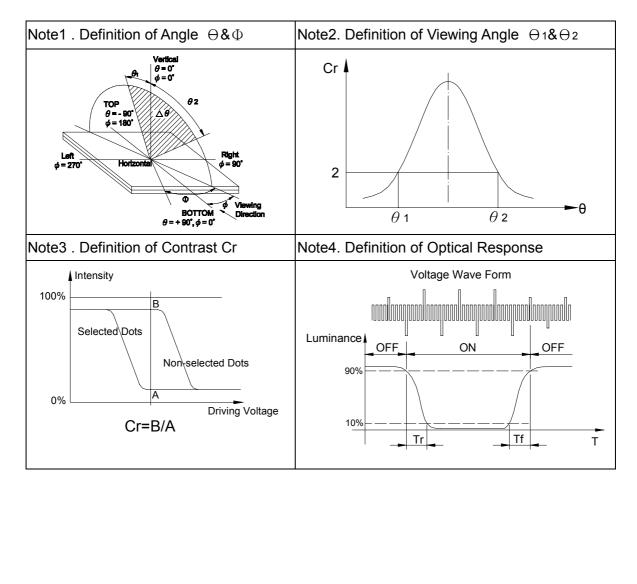
4-3-2. Opto-electronic Characteristics

ltem	Symbol	Condition	Min.	Тур.	Max	Unit
Forward Voltage	VF	Ta= 25 ℃	-	5.0	5.5	V
Luminous	-	IF= 100mA	35	-	-	cd/m²

L					
	MODEL	LMG1286410A-YTDSYW-NY	4/25	PRODUCT SPECIFICATIONS	REV:A



ltem	Symbol	Temp.	Min.	Тур.	Max.	Unit	Conditions	Note
Viewing	⊖2−⊖1	25 ℃	30	80	-	Dea		1.0
Angle	<u> </u>	250	60	85	-	Deg.	-	1,2
Contrast Ratio	Cr	25 °C	2	5.3	5.9	-	⊖=0° ⊕=0°	3
Response	т.	25 ℃	-	91	250		⊖=0°	
Time(rise)	Tr	0 °C	-	950	1150	ms	Ф =0°	4
Response	Τf	25 °C	-	151	250		⊖=0°	
Time(fall)	Τf	0 °C	-	950	1150	ms	⊕=0°	4

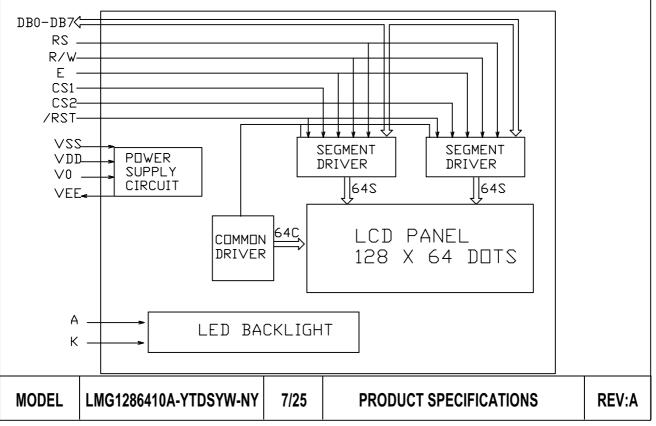


MODEL	LMG1286410A-YTDSYW-NY	6/25	PRODUCT SPECIFICATIONS	REV:A
-------	-----------------------	------	------------------------	-------

7.TERMINAL FUNCTIONS AND BLOCK DIAGRAM 7-1.INTERFACE PIN FUNCTION DESCRIPTION

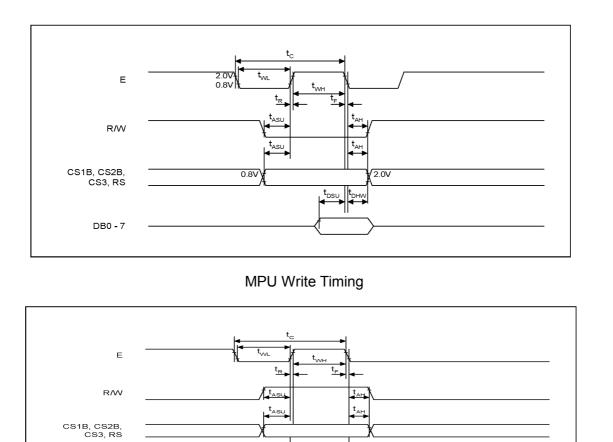
ND.	SYSBOL	DESCRIPTION
1	VDD	POWER SUPPLY FOR LOGIC AND LCD
2	VSS	GREUND
3	$\vee 0$	OPERATING VOLTAGE FOR LCD
4	DBO	DATA BUS
5	DB1	DATA BUS
6	DB2	DATA BUS
7	DB3	DATA BUS
8	DB4	DATA BUS
9	DB5	DATA BUS
10	DB6	DATA BUS
11	DB7	DATA BUS
12	/CS2	CHIP SELECT OF IC2 (LOW EFFECTIVE)
13	/CS1	CHIP SELECT OF IC1 (LOW EFFECTIVE)
14	/RST	RESET SIGNAL(LOW EFFECTIVE)
15	R/W	READ/WRITE SELECT
16	RS	DATA/INSTRUCTION SELECT
17	E	ENABLE SIGNAL
18	VEE	NEGATIVE VOLTAGE OUTPUT/INPUT
19	К	BACKLIGHT-
20	А	BACKLIGHT+

7-2.BLOCK DIAGRAM



8. TIMING CHARACTERISTICS

Characteristic	Symbol	Min	Тур	Мах	Unit
E cycle	t _C	1000	-	-	ns
E high level width	t _{WH}	450	-	-	ns
E low level width	t _{WL}	450	-	-	ns
E rise time	t _R	-	-	25	ns
E fall time	t _F	-	-	25	ns
Address set-up time	t _{ASU}	140	-	-	ns
Address hold time	t _{AH}	10	-	-	ns
Data set-up time	t _{DSU}	200	-	-	ns
Data delay time	t _D	-	-	320	ns
Data hold time (write)	t _{DHW}	10	-	-	ns
Data hold time (read)	t _{DHR}	20	-	-	ns



MODEL LMG1286410A-YTDSYW-NY 8/25 PRODUCT SPECIFICATIONS REV:A

9. INSTRUCTION SET

9-1. Function of Each Block

Both input register and output register are provided to interface with MPU of which The speed is different from that of internal operation. The selection of these registers Registers depend on the combination of R/W and D/I signals.

Table1.	Register	selection	

D/I	R/W	Operation
1	1	Read data out of output register as internal operation (Display data RAM to output register)
1	0	Writes data into register as internal operation (Input register to display data RAM)
0	1	Busy check. Read of status data
0	0	Instruction

(1) Input Register

Input register is used to store Data temporarily before writing it into display data RAM. The data from MPU is written into input register, then into display data RAM Automatically by internal operation.

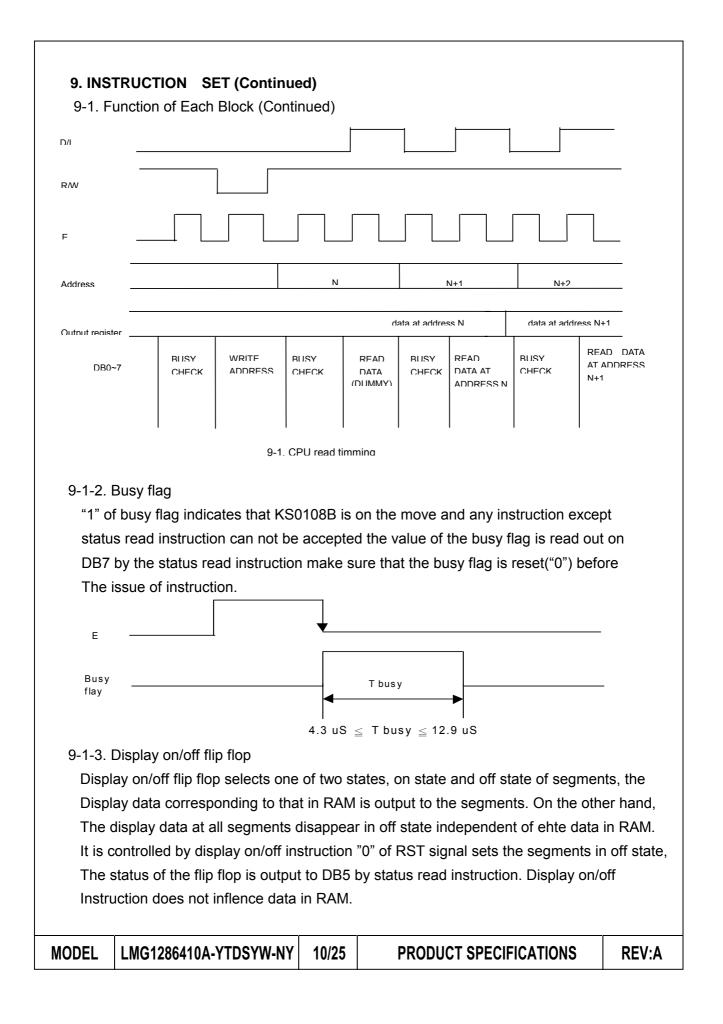
When chip select signal is in the active mode and D/I and R/W select the input Register as shown in table1, Data is latched at the fall of "E" signal.

(2) Output register

The output register is used to store data temporarily that is read from display data RAM. To read out the data from output register. Chip select signal should be in the Active mode and both D/I and R/W should be "1". With the read instruction, data stored in the output register is output while "E", the display data at the indicated address is latched into the output register and address is increased by 1. The contents in the output register is rewritten by read instructions, but are held by address set instruction, ect.

Therefore, the data of the specified address can not be output with read display Instruction, right after the address is set, but can be output at the second read of data. That is to say, on dummy read is necessary, Fig 9-1. Shows the CPU read timming.

9/25



9. INSTRUCTION SET (Continued)

9-1-4. Display start register

The register specifies A line in RAM which corresponds to the top line of LCD panel, When displaying contents in display data RAM on the LCD panel. It is used for scrolling Of the screen. 6-bit display start line information is written into this register by display Start the display, the information in this register is transferred to Z address, and the Z Address counter is preset.

9-1-5. X, Y address counter

This is 9 bit counter which designates address of internal display data RAM, X address Counter of upper 3 bits and Y address counter of lower 6 bits should be set each Address by respective instruction.

(1). X address counter

Ordinary register with no count functions. An address is set in by instruction.

(2). Y address counter

An address is set in by instruction and it is increased by 1 automatically by R/W Operations of display data. The address counter loops the value of 0 to 63 count.

9-1-6. Display data RAM

Dot data for display is stored in this RAM 1 bit data of this RAM corresponds to light on (data=1) and light off (data=0) of 1 dot in the display panel.

9-1-7. Reset

The system can initialized by setting RST terminal at "low" level when turning power on.

(1) Display off

(2) Set display start line register 0 line.

When RST is in low level, any instruction except status read can not be accepted, Therefore, carry out other instruction after making sure that DB4="0" (clear reset) And DB7="0" (ready) by status read instruction the conditions of power supply at Initial power up are as follows.

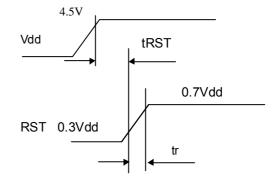
MODEL LMG1286410A-YTDSYW-NY	11/25	PRODUCT SPECIFICATIONS	REV:A
-----------------------------	-------	------------------------	-------

9. INSTRUCTION SET (Continued)

9-1-7. Reset (Continued)

Item	Symbol	Min.	Тур.	Max.	Unit
Reset time	tRST	1.0	_	Ι	uS
Rise time	tr	_	_	200	uS

Do not fail to set the system again because resetduring operation may destroy the data in all the register except on/off register and in RAM



9-2. Display control instructions

Table 2 shows the instructions. Read/write (R/W) signal, data instruction (D/I) sihnal and data bus signal (DB0 to DB7) are also called instructions because the internal operation depends on the signal from MPU generally, there are following three kinds of instructions.

- 1) Instruction to give address in the internal RAM
- 2) Instruction to transfer data from/to the internal RAM
- 3) Other instructions.

In general use, the instruction"2)" are used most frequently, but , since Y address of the internal RAM is increased by 1 automatically after writing (reading) data, the program can be lessened, during the execution of an instruction, the system can not accept other instructions than status read instruction, send instruction from MPU after making sure if the busy flag is "0", which is the proof an instruction is not being executed.

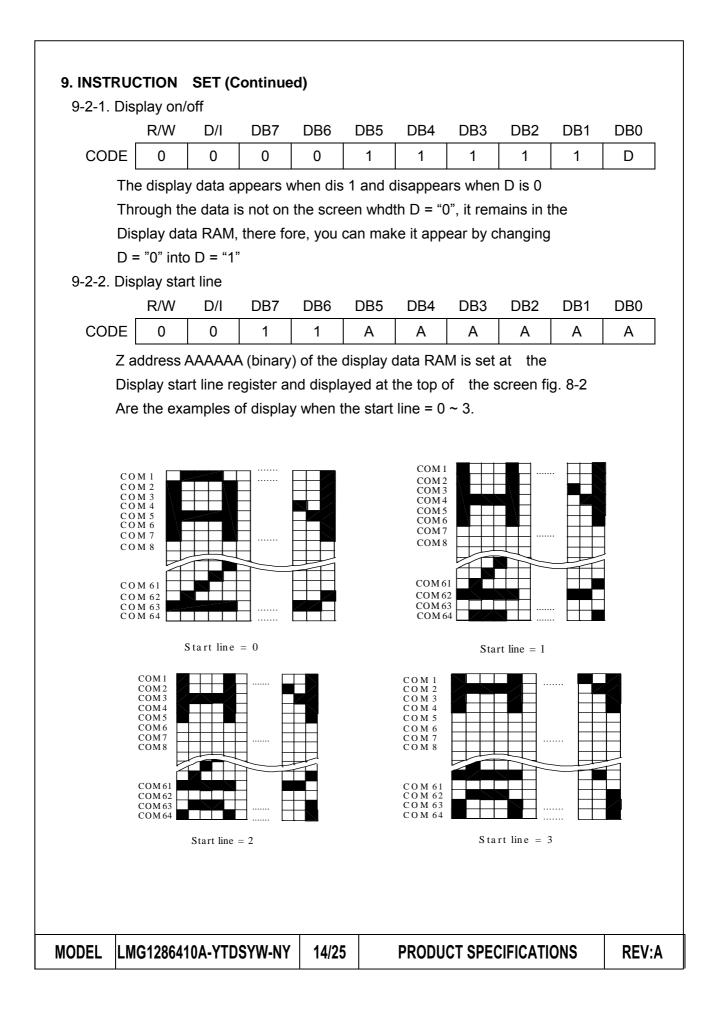
MODEL LMG1286410A-YTDSYW-NY 12/25 PRODUCT SPECIFICATIONS R
--

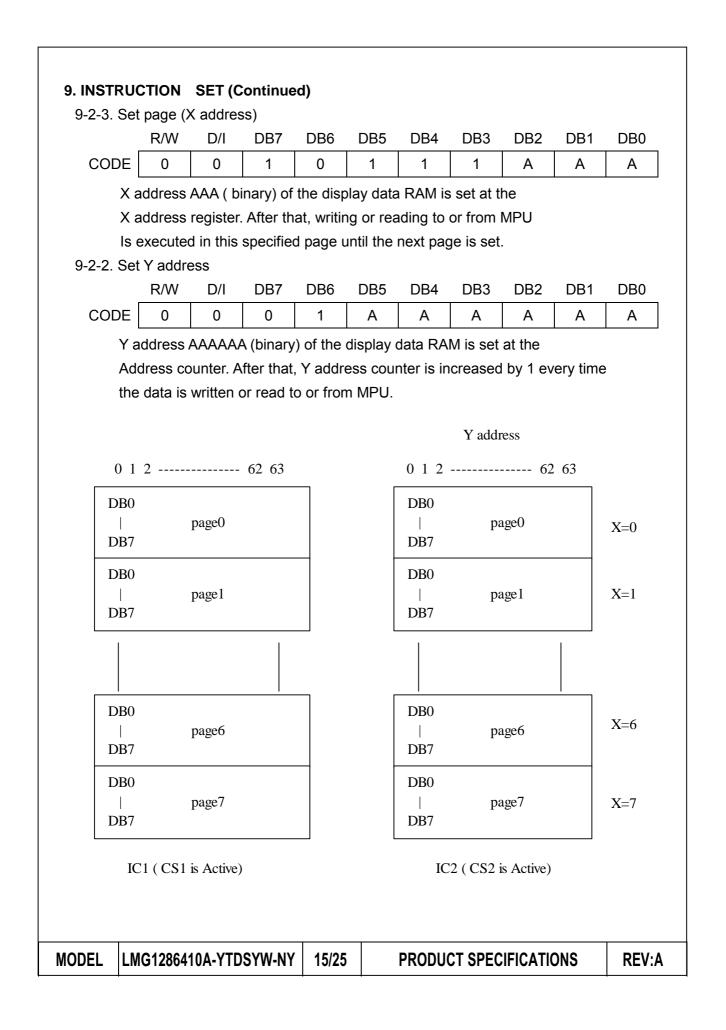
9. INSTRUCTION SET (Continued)

Table 2

	D	R	D	D	D	D	D	D	D	D			
Function	/	1	В	D	В	В	В	В	В	В	Description		
	Ι	W	7	6	5	4	3	2	1	0			
Display On/Off	0	0	0	0	1	1	1	1	1	0/1	Controls the on/off display RAM data and internal status are not affected. 0 : off ; 1: on.		
Set Address	0	0	0	1	١	⁄ ad	dres	ss (0 ~ 63)			Sets the Y address in the Y address counter.		
Set Page (X address)	0	0	1	0	1	1	1	Page(0~7)			Sets the X address in the X address register.		
Display Start Line	0	0	1	1	Display start line (0~63)			ne (0	~63)	Indicates the display data RAM Displayed at the top of the screen.			
Status Line	0	1	B U S Y	0		R E S E T	0	0	0	0	Read status: BUSY : 0: Ready 1: In operation ON/Off 0: Display ON 1: Display Off RESET 0: Normal 1: Reset		
Write display Data	1	0		Write Data							Writes data (DB0~7) into display Data RAM. After writing instruction, Y address is increased by 1 automatically.		
Read display Data	1	1		Read Data							Reads data (DB0~7) into display data RAM to the data bus.		

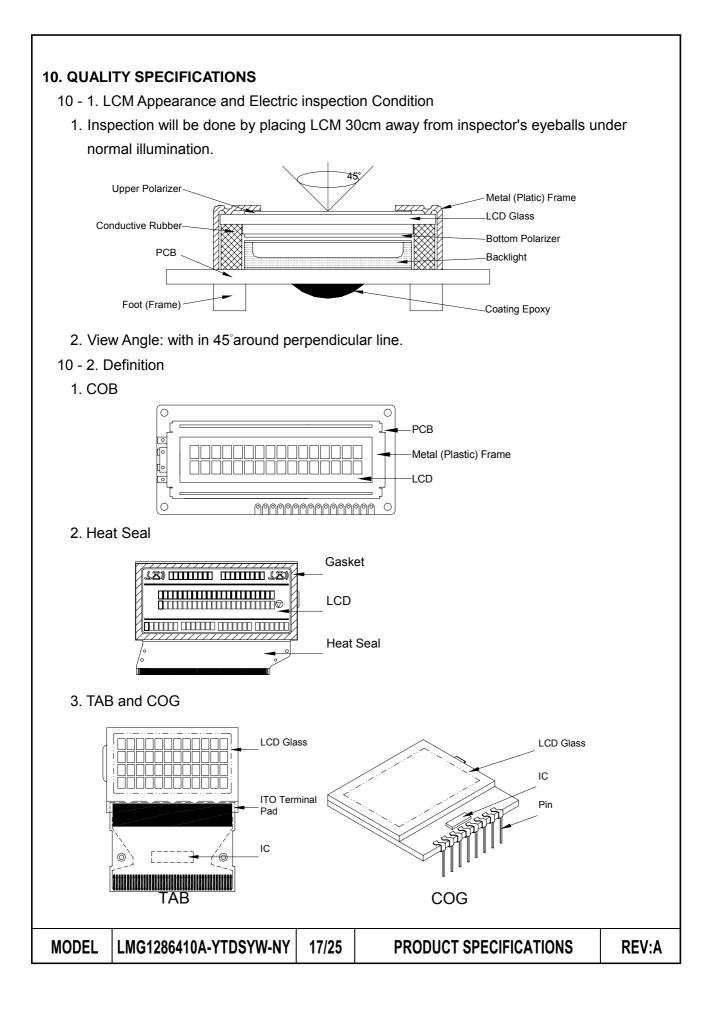
MODEL	LMG1286410A-YTDSYW-NY	13/25	PRODUCT SPECIFICATIONS	REV:A





9. INSTRUCTION SET (Continued)										
9-2-5.	Status read									
	R/W	D/I	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
COD)E 1	0	Busy	0	On/Off	Reset	0	0	0	0
BusyII<										
9-2-6.	Write display R/W	∕ data D/I	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
COD	E 0	1	А	А	А	А	А	А	Α	А
Write 8-bit data AAAAAAA (binary) into the display data RAM then Y address is increased by 1 automatically. 9-2-7. Write display data										
COD	R/W E 1	D/I 1	DB7 A	DB6 A	DB5 A	DB4 A	DB3 A	DB2 A	DB1 A	DB0 A
Read out 8-bit data AAAAAAAA (binary) from the display data RAM then Y address is increased by 1 automatically. One dummy read is necessary soon after the address seting.										
MODEL	LMG128641	0A-YTD	SYW-NY	16/25		PRODUC	CT SPEC	IFICATIO	ONS	REV:A

Г



10. QUALITY SPECIFICATIONS (Continued)

10-3. Sampling Plan and Acceptance

1.Sampling Plan

MIL - STD - 105E (\parallel) ordinary single inspection is used.

2. Acceptance

Major defect:	AQL = 0.25%
Minor defect:	AQL = 0.65%

10-4. Criteria

1.COB

Defect	Inspection Item	Inspection Standards		
Major	PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm ²	Reject	
Major	Height of coating epoxy	Exceed the dimension of drawing	Reject	
Major	Void or hole of coating epoxy	Expose bonding wire or IC	Reject	
Major	PCB cutting defect	Exceed the dimension of drawing	Reject	

2.SMT

Defect Inspectio		on Item	Inspection Standa	ards
Minor	Component marki	ng not readable		Reject
Minor	Componer	nt height	Exceed the dimension Of drawing	Reject
Major	Component solder defe wrong component or w			Reject
Minor	Component p component X \rightarrow \downarrow \downarrow \downarrow \downarrow \downarrow \downarrow \downarrow \downarrow \downarrow \downarrow		X < 3/4Z Y > 1/3D	Reject Reject
Minor	Compon	ent tilt component	Y > 1/3D	Reject
Minor		t solder component PAD CB	<i>θ</i> <u>≤</u> 20°	Reject
	G1286410A-YTDSYW-NY	18/25 PROE	OUCT SPECIFICATIONS	REV

10. QUALITY SECIFICATIONS (Continued)

10-4. Criteria (Continued)

3. Metal (Plastic) Frame

Defect	Inspection Item	h	nspection Standa	rds	
Major	Crack / breakage	Any	/where	Reject	
		W	L	Acceptable of Scratch	
		w<0.1mm	Any	Ignore	
		0.1 <u><</u> w<0.2mm	L <u><</u> 5.0mm	2	
Minor	Frame Scratch	0.2 <u><</u> w<0.3mm	L <u><</u> 3.0mm	1	
		w <u>></u> 0.3mm	Any	0	
		Note : 1. Above criteria applicable to scratch lines with distance greater than 5mm. 2. Scratch on the back side of frame (not visible) can be ignored .			
				Acceptable of Dents / Pricks	
		Φ <u><</u>	1.0mm	2	
	Frame Dent , Prick	1.0<₫	⊃ <u><</u> 1.5mm	1	
Minor	$\Phi = \frac{L + W}{2}$	1.5	mm< Φ	0	
	2	/ pricks with dis	e criteria applicable tance greater than / prick on the back s ignored	5mm	
Minor	Frame Deformation	Excee	d the dimension of	drawing	
Minor	Metal Frame Oxidation		Any rust		

4. Flexible Film Connector (FFC)

Defect	Inspection Item	Inspection Standa	rds	
Minor	Tilted soldering	Within the angle +5°	Accep	table
Minor	Uneven solder joint /bump		Rej	ect
Minor	Hole $\Phi = \frac{L + W}{2}$	Expose the conductive line	Rej	ect
IVIITIO	Hole Ψ^- 2	Φ > 1.0mm	Rej	ect
Minor	Position shift $Y \xrightarrow{-\frac{1}{2}} $	Y > 1/3D	Rej	ect
WIITIOI		X > 1/2Z	Rej	ect
	G1286410A-YTDSYW-NY 19	/25 PRODUCT SPECIFICAT	IONS	REV

10. QUALITY SPECIFICATIONS (Continued)

10-4. Criteria (Continued)

5. Screw

Inspection Item	Inspection Standards	
Screw missing/loosen		Reject
Screw oxidation	Any rust	Reject
Screw deformation	Difficult to accept screw driver	Reject
-	Screw missing/loosen Screw oxidation	Screw missing/loosen Screw oxidation Any rust

6. Heatseal $\$ TCP $\$ FPC

Defect	Inspection Item	Inspection Standards	
Major	Scratch expose conductive layer		Reject
Minor	HS Hole $\Phi = \frac{L + W}{2}$	⊕> 0.5mm	Reject
Major	Adhesion strength	Less than the specification	Reject
Minor	Position shift	Y > 1/3D	Reject
		X > 1/2Z	Reject
Major	Conductive line break		Reject

7. LED Backing Protective Film and Others

Defect	Inspection Item	Inspection Standards				
		Acceptable number of units				
Minor LED dirty, prick		⊕ <u><</u> 0.10mm	Ignore			
		0.10<⊕ <u><</u> 0.15mm	2			
	0.15<⊕ <u><</u> 0.2mm	1				
		⊕>0.2mm	0			
		The distance between any two spots should be <u>></u> 5mm Any spot/dot/void outside of viewing area is acceptable				
Minor	Protective film tilt	Not fully cover LCD Re				
Major	COG coating	Not fully cover ITO circuit Re				

8. Electric Inspection

Defect	Inspection Item	Inspection Standards	
Major	Short		Reject
Major	Open		Reject

MODEL	LMG1286410A-YTDSYW-NY	20/25	PRODUCT SPECIFICATIONS	REV: A	
-------	-----------------------	-------	------------------------	--------	--

10. QUALITY SPECIFICATIONS (Continued)

10-4. Criteria (Continued)

10. Inspection Specification of LCD

ar Defect Spot and olarizer Pricked	 Glass Scrat Polarizer Sc Fiber and Li material Foreign mat between glass polarizer or gla 	cratch inear terial	W L ACC. NO. Note	W	/ <u><</u> 0.03 L<5	0.	03 <w<u><0.0 L<3</w<u>	5 V	W>0.05 Any
< Spot and olarizer	 * Polarizer So * Fiber and Li material * Foreign material between glass polarizer or gla 	cratch inear terial	ACC. NO. Note				L<3		Δηγ
< Spot and olarizer	 Fiber and Li material Foreign mat between glass polarizer or gla 	inear terial	NO. Note						Ally
olarizer	material Foreign mat between glass polarizer or gla 	terial	Note	1	1		1		Reject
olarizer	* Foreign mat between glass polarizer or gla			1 :- 41 1					
olarizer	between glass polarizer or gla				-		ne width of		
olarizer	polarizer or gla		Φ ACC.	Φ <u><</u> 0.1 3EA /		0.15	0.15<⊕ <u><</u> 0	.2	⊕>0.2
olarizer			NO.	100mm	2 2		1		0
	and glass * Polarizer ho protuberance b external force	ole or	Note	Φ is the	e average (er of the de fects > 10n		
	* Unobvious		Φ	Φ	<u><</u> 0.3	0.3	< <u>0.5</u>	0.	. 5 <Φ
nite Spot	transparant for material betwe	en	ACC. NO.	3EA /	100mm ²		1		0
Bubble in plarizer	glass and glas glass and pola * Air protuber between polari and glass	arizer rance	Note		-		er of the de fects > 10n		
			Φ	⊕ <u><</u> 0.10	0.10<	. <u><</u> 0.20	0.20<Φ <u><</u>	<u><</u> 0.25	⊕>0.25
		F.	ACC. NO.	3EA / 100mm	2 2		1		0
Segment Defect	J	W is more than 1/2 segment width					Reject		
			Note	⊕= <u> L</u> Distance	2	two de	fect is 10m	m	
			Φ	Φ <u><</u> 0.10	0.10<	<u><</u> 0.20	0.20<Φ<	<u><</u> 0.25	Φ>0.25
utuberant egment	W W		W	Glue	W <u><</u> 1/2 W<	2 Seg	W <u><</u> 1/2 ₩≤0		Ignore
sginon	Φ = (L + W) / 2	2	ACC. NO.	3EA / 100mm	2 2		1		0
			1. Seg						
			В	3	3 <u><</u> 0.4mm	0.4<	3 <u><</u> 1.0mm	B>?	1.0mm
			B-	A	3-A<1/2B	B	A<0.2	B-A	<0.25
sembly alignment		A	Jud		cceptable		eptable		eptable
			2. Dot	-			• -		
		₽ ₹	Defo	ormation	>2°				Reject
n on LCD el Surface			oras	similar o	ne. Other	wise, j	udged aco	cordin	
									REV:
				Surface or a state	Surface or a similar o above items: "E	Surface or a similar one. Other above items: "Black spot"	Surface or a similar one. Otherwise, j above items: "Black spot" and "W	Surface or a similar one. Otherwise, judged acc above items: "Black spot" and "White Spot"	lor a similar one ()therwise judged accordin

11. RELIABILITY

NO.	ltem	Condition	Criterion
1	High Temperature Operating	70℃, 240Hrs	
2	Low Temperature Operating	- 2 0 ℃, 240Hrs	
3	High Humidity	60℃, 90%RH, 96Hrs	
4	High Temperature Storage	80℃, 240Hrs	
5	Low Temperature Storage	-30℃, 240Hrs	No defect in cosmetic and operational
		Random wave	function allowable.
6	Vibration	10 ~ 100Hz	Total current Consumption should be below double of
		Acceleration: 2g	initial value.
		2 Hrs per direction(X,Y,Z)	
		-30℃ to 25℃ to 80℃	
7	Thermal Shock	(60Min) (5Min) (60Min)	
		10Cycles	
0	ESD Testing	Contract Discharge Voltage: +1 ~ 5kV and –1 ~ –5kV	There will be discharged ten times at every discharging
8	LOD resuring	Air Discharge Voltage: +1 ~ 8kV and –1 ~ -8kV	voltage gap is 1kV.

Note: 1) Above conditions are suitable for GOLDENTEK standard products.

2) For restrict products, the test conditions listed as above must be revised.

MODEL LMG1286410A-YTDSY	W-NY 22/25	PRODUCT SPECIFICATIONS	REV: A
-------------------------	------------	------------------------	--------

12. HANDLING PRECAUTION

(1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizers which easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling the LCD Modules.

(1) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommended below) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Trichloro trifloro thane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Ketone
- Aromatics
- (3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before power is turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

- (4) Packaging
 - Modules use LCD elements, and must be treated as such. Avoid intense shock and falls from a height.
 - To prevent modules from degradation. Do not operate or store them exposed directly to sunshine or high temperature/humidity.
- (5) Caution for operation
 - It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.

MODEL LMG1286410A-YTDSYW-NY 23/25	PRODUCT SPECIFICATIONS	REV:A
-----------------------------------	------------------------	-------

12. HANDLING PRECAUTION (Continued)

- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them.

However those phenomena do not mean malfunction or out of order with LCD's. Which will come back in the specified operating temperature range.

- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

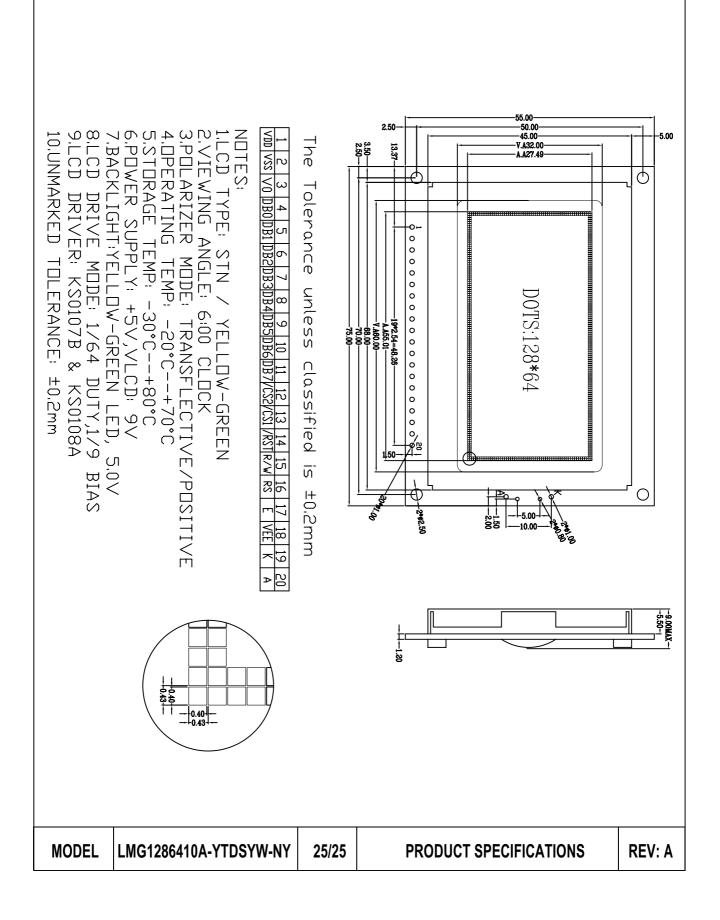
Usage under the relative condition of 40°C, 50%RH or less is reequired.

(6) Storage

In the case of storing for a long period of time (for instance.) For years) for the purpose or replacement use, The following ways are recommended.

- Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is. Keeping temperature in the specified storage temperature range.
- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)
- (7) Safety
 - It is recommendable to crash damaged or unnecessary LCD into pieces and wash off liquid crystal by using solvents such as acetone and ethanol.
 - Which should be burned up later.
 - When any liquid crystal leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

	MODEL	LMG1286410A-YTDSYW-NY	24/25	PRODUCT SPECIFICATIONS	REV: A	
--	-------	-----------------------	-------	------------------------	--------	--



13. OUTLINE DIMENSION